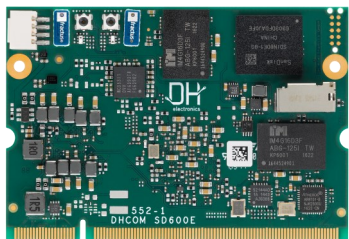


# DHCOM SD600E

## Pluggable, compatible SOM



### TECHNICAL DETAILS

Processor	Qualcomm® Snapdragon™ 600E 4 Krait™ 300 Cores up to 1.5 GHz
CPU features	Qualcomm® Adreno™ 320 2D/3D graphics acceleration
DDR3 DRAM	1024 / 2048 Mbyte
eMMC flash	4 / 8 / 16 / 32 Gbyte
E²Prom	128 byte
microSD socket	Available on module
Battery	Battery charger and connector
Real-time clock RTC	Available on module
WLAN	Dual-band 2.4 GHz and 5 GHz with 802.11a/b/g/n support
Bluetooth	BT 4.0 EDR + BLE compliant
Antenna	SMP connectors and Chip antennas
Sensors <sup>[1]</sup>	Magnetometer, Accelerometer and Gyroscope
Supply	3.3 or 5.0 VDC / typ. 2.0-4.0 W
Temperature range	-25 to +70 °C
Dimensions	67.6 x 45.7 x 8.1 mm
Debug interface	JTAG interface on module
BSPs	Linux (Yocto or Debian based) and Android 5.0 or newer

### SODIMM-200 SOCKET

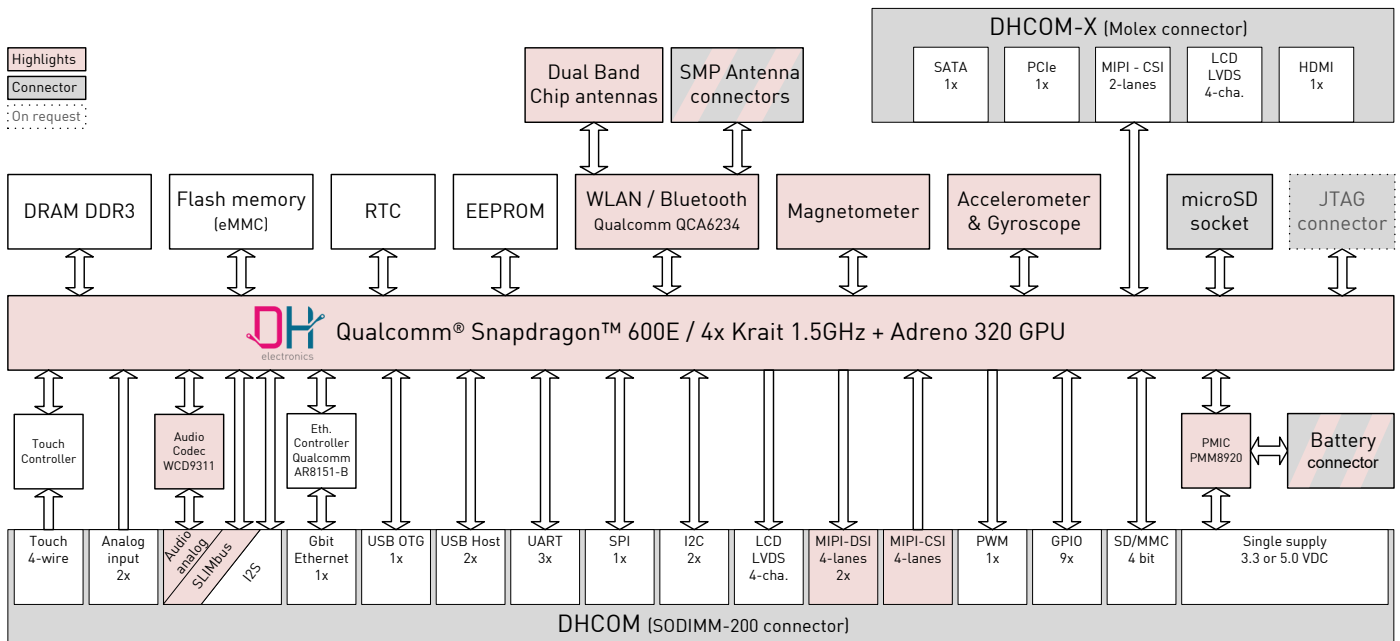
Bus interface (parallel)	-
Ethernet 1 <sup>[4]</sup>	10 / 100 / 1000 Mbit/s
Ethernet 2	-
MMC/SD interface	4 bit mode
CAN	-
UART 1	Rx / Tx / Rts / Cts, up to 4.0 Mbit/s
UART 2	Rx / Tx / Rts / Cts, up to 4.0 Mbit/s
UART 3	Rx / Tx, up to 4.0 Mbit/s
SPI 1	max. 52 MHz
SPI 2	-
I2C 1	max. 400 kbit
I2C 2	max. 400 kbit
USB host 1	High-Speed
USB host 2	High-Speed
USB OTG	High-Speed
CSI (parallel camera)	-
Display RGB	-
Display LVDS 1 <sup>[2]</sup>	Max. 2048 x 1536 @60 fps
MIPI DSI 1 (display)	4-data lanes 2048 x 1536 @60 fps
MIPI DSI 2 (display)	On request
MIPI CSI 2 (camera)	4-data lanes up to 4096 Mbit/s
Touch	4-wire
I2S <sup>[3][1]</sup>	1
Analog audio <sup>[3]</sup>	1 Mic. In, 1 Line In, 1 Headphone Out
SLIMbus <sup>[3]</sup>	1
GPIOs	9 IOs
PWM	1
Analog inputs	2 10bit

### HIGH SPEED SOCKET

RGMII (Gbit Ethernet)	-
Sata	Serial ATA Rev. 1.0
PCIe <sup>[4]</sup>	1-lane PCIe 2.0 compliant
MIPI CSI 1 (camera)	2-data lanes up to 2048 Mbit/s
Display LVDS 2 <sup>[2]</sup>	Max. 2048 x 1536 24bit @60 fps
HDMI	Max. 1080p @60 Hz, HDMI 1.4a

<sup>[1]</sup> Alternate usage between I2S interface and Onboard Accelerometer, Gyroscope and Magnetometer sensors. <sup>[2]</sup> Max. resolution is possible with dual channel LVDS, by using interface LVDS 1 and LVDS 2. <sup>[3]</sup> Alternate usage between I2S, SLIMbus and analog audio. <sup>[4]</sup> Either PCIe on High Speed connector or Gbit Ethernet on SODIMM-200 connector. **magenta = optionally**

### BLOCK DIAGRAM



### ORDERING INFORMATION

Ordering Configurations: DHCM-SD600E-Rxxx[-Fxxxx][-E][-SD][-RTC][-T][-A/-I2S][-WBT][-S][-ADC][-BAC][-HS]-E-01D2

SD600E	Qualcomm® Snapdragon™ 600E (APQ8064E) / 4x Krait™ Cores up to 1.5GHz + Adreno™ 320 GPU
Rxxx	1GByte : R102, 2GByte : R204
E	Extended temperature range (-25°C to 70°C)
01D2	DHCOM Revision, SODIMM200 socket
	DHCOM Revision, SODIMM200 socket

### Options

[-Fxxxx]	4GByte eMMC: F0409, 8GByte eMMC: F0819, 16GByte eMMC: F1638, 32GByte eMMC: F3276
[-E]	Gbit Ethernet Controller (PCIe is connected to high speed connector without Option E)
[-SD]	microSD socket
[-RTC]	Low power temperature compensated real time clock (instead of CPU internal RTC)
[-T]	Resistive touch controller
[-A] or [-I2S]	Audio Codec: A, I2S: I2S (SLIMbus is connected without Option A or I2S)
[-WBT]	WLAN and Bluetooth with chip antennas and SMP connectors
[-S]	Magnetometer, Accelerometer and Gyroscope sensors
[-ADC]	AD-Converter inputs
[-BAC]	Battery connector
[-HS]	High speed interface connector

### Item number

HQ00003

### Model (other configurations on request)

DHCM-SD600E-R204-F0819-E-SD-RTC-T-A-WBT-S-ADC-BAC-HS-E-01D2

### Product description

DHCOM SD600E, 2GB DRAM, 8GB eMMC flash, ethernet, microSD slot, RTC, res. touch, audio codec, WLAN and bluetooth, sensors (Magnetometer, Accelerometer & Gyroscope), ADC, battery connector, high speed connector, ext. Temp. range

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